

ABSTRACT

A film forming method of forming a film made of a curable composition, includes an arranging step of arranging the curable composition on an underlayer of a substrate including a base member and the underlayer arranged on the base member, a contact step of bringing the curable composition and a mold into contact with each other after the arranging step, a curing step of curing the curable composition after the contact step, and a separation step of separating the curable composition and the mold after the curing step, wherein a gas filling a space between the underlayer and the mold exists in the contact step, and a solubility coefficient of the gas with respect to the underlayer is $0.5 \text{ kg/m}^3 \cdot \text{atm}$ or more and $10 \text{ kg/m}^3 \cdot \text{atm}$ or less.